

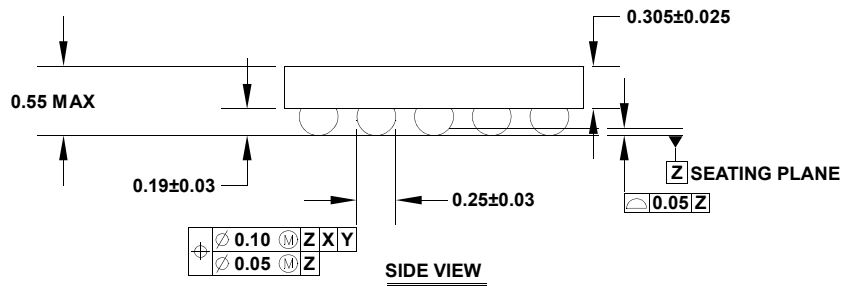
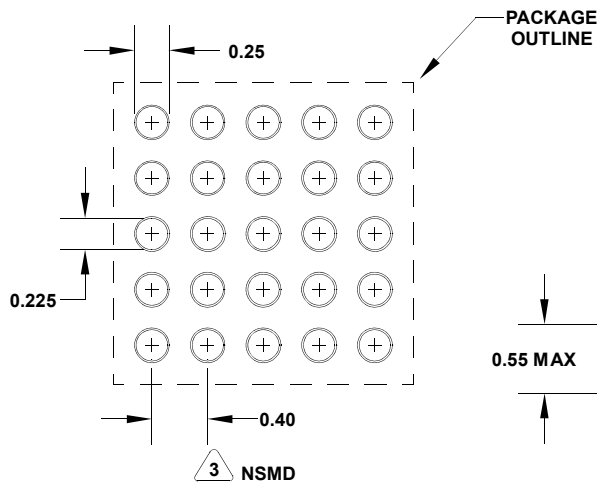
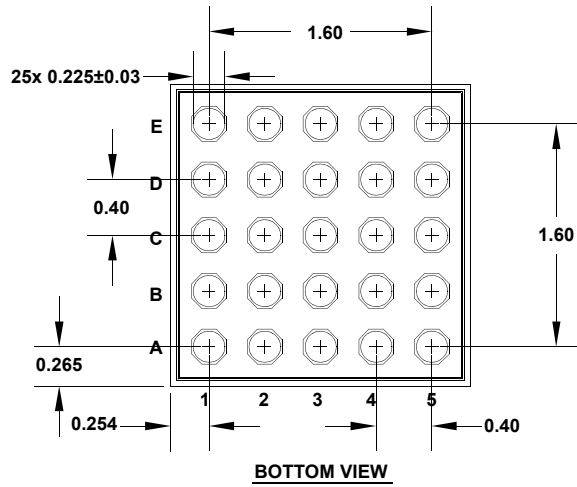
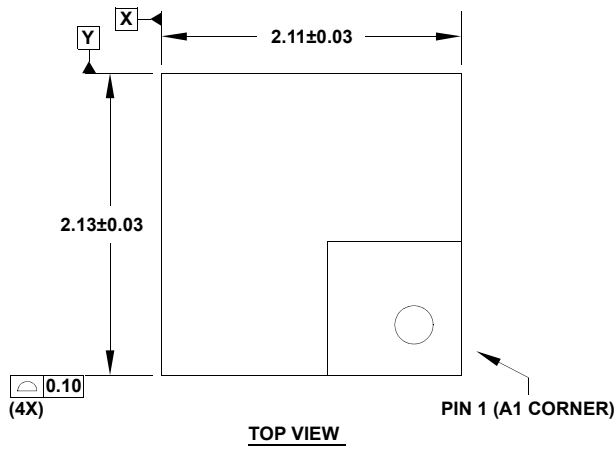
Plastic Packages for Integrated Circuits

Package Outline Drawing

W5x5.25B

5x5 ARRAY 25 BALL WITH 0.40 PITCH WAFER LEVEL CHIP SCALE PACKAGE (WLCSP)

Rev 2, 12/11



NOTES:

1. All dimensions are in millimeters.
2. Dimension and tolerance per ASMEY 14.5M-1994, and JESD 95-1 SPP-010.
3. NSMD refers to Non-Solder Mask Defined pad design per Intersil Tech Brief TB451 located at: <http://www.intersil.com/data/tb/tb451.pdf>.